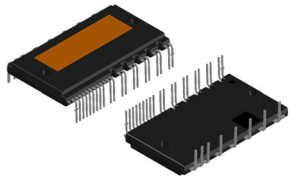


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



DIP39, 54.50x31.00x5.60, 1.78P EP-2 CASE MODGX ISSUE A

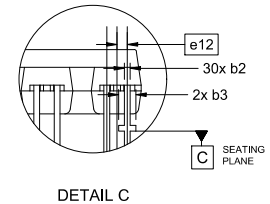
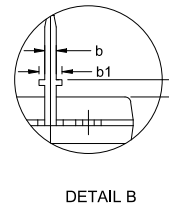
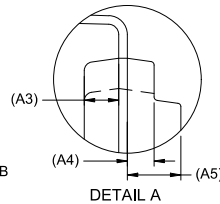
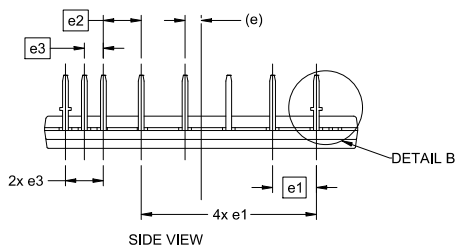
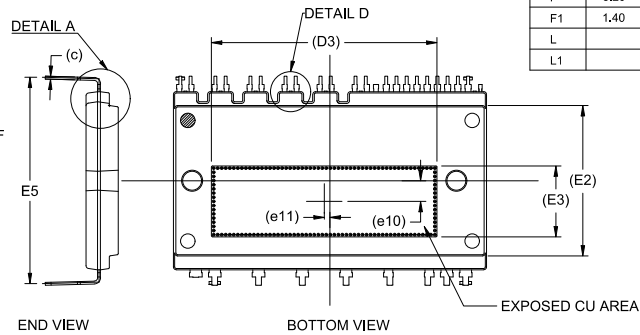
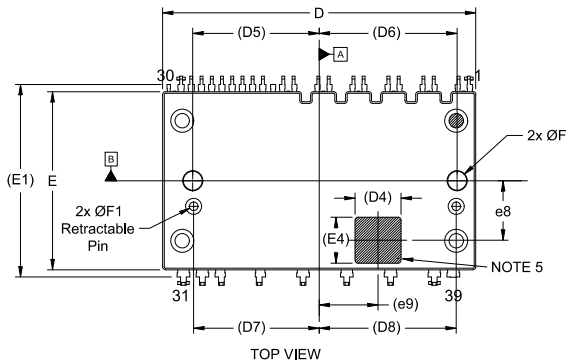
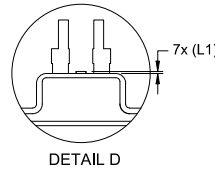
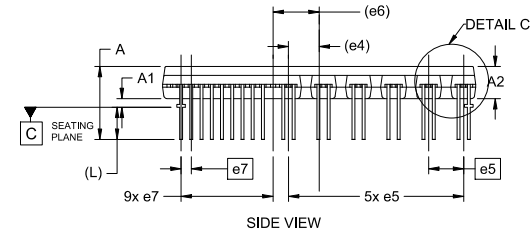
DATE 20 DEC 2023

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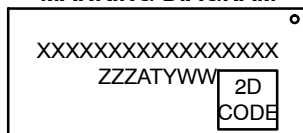
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b and c APPLY TO THE PLATED LEADS AND ARE MEASURED BETWEEN 1.00 AND 2.00 FROM THE LEAD TIP
4. POSITION OF THE LEAD IS DETERMINED AT THE BASE OF THE LEAD WHERE IT EXITS THE PACKAGE BODY
5. AREA FOR 2D BAR CODE
6. SHORTENED/CUT PINS ARE 2,5,8,11,14,17,19,29, 30 AND 39

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	12.20	12.7	13.2
A1	1.00	1.50	2.00
A2	5.50	5.60	5.70
A3	2.00 REF		
A4	1.55 REF		
A5	3.10 REF		
b	0.90	1.00	1.10
b1	1.90	2.00	2.10
b2	0.40	0.50	0.60
b3	1.40	1.50	1.60
c	0.50 REF		
D	54.40	54.50	54.60
D3	39.25 REF		
D4	8.00 REF		
D5	22.00 REF		
D6	24.00 REF		
D7	21.85 REF		
D8	23.85 REF		

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
E	30.90	31.00	31.10
E1	33.50 REF		
E2	26.14 REF		
E3	12.35 REF		
E4	8.00 REF		
E5	35.40	35.90	36.40
e	2.81 REF		
e1	7.62 BSC		
e2	6.60 BSC		
e3	3.30 BSC		
e4	5.35 REF		
e5	6.10 BSC		
e6	8.02 REF		
e7	1.78 BSC		
e8	10.35 REF		
e9	10.25 REF		
e10	3.60 REF		
e11	1.00 REF		
e12	0.89 BSC		
F	3.20	3.30	3.40
F1	1.40	1.50	1.60
L	5.60 REF		
L1	0.10 REF		



GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
 ZZZ = Assembly Lot Code
 AT = Assembly & Test Location
 Y = Year
 WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	DIP39, 54.50x31.00x5.60, 1.78P EP-2	PAGE 1 OF 1

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